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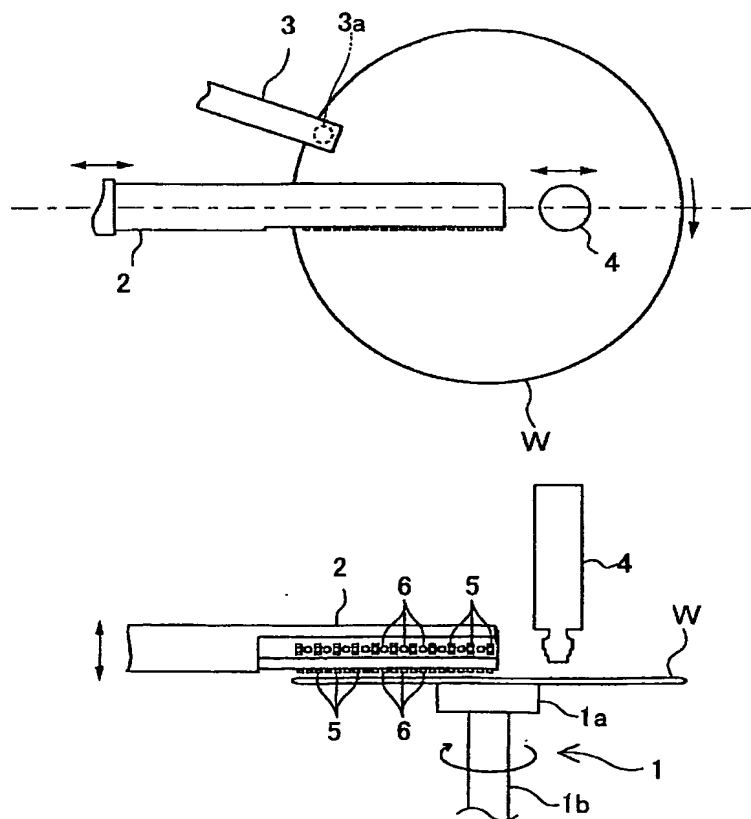
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(54) Title: A PROCESSING LIQUID COATING APPARATUS AND A PROCESSING LIQUID COATING METHOD



(57) Abstract: The present invention relates to a processing liquid coating apparatus and a processing liquid coating method suitable for use in a lithography process for forming fine circuit patterns on a surface of a substrate such as a semiconductor wafer. The processing liquid coating apparatus according to the present invention includes a substrate holder (1) for holding and rotating a substrate (W), and a processing liquid supply unit (2) disposed apart from the substrate (W) held by the substrate holder (1). The processing liquid supply unit (2) has a plurality of supply ports (5, 6) for supplying a processing liquid to a plurality of portions including a central portion (C) of a surface of the substrate (W). A resist liquid or a developer is used as the processing liquid.

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